

AP70L02GH/J

Pb Free Plating Product



**Advanced Power
Electronics Corp.**

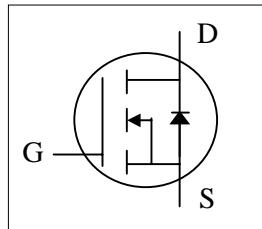
N-CHANNEL ENHANCEMENT MODE

POWER MOSFET

▼ Low Gate Charge

▼ Simple Drive Requirement

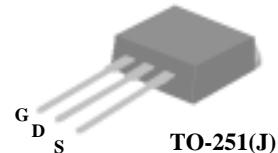
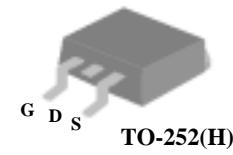
▼ Fast Switching



BV_{DSS}	25V
$R_{DS(ON)}$	9mΩ
I_D	66A

Description

The TO-252 package is universally preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters. The through-hole version (AP70L02GJ) is available for low-profile applications.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	25	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	66	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	42	A
I_{DM}	Pulsed Drain Current ¹	210	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	66	W
	Linear Derating Factor	0.53	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal Resistance Junction-case	Max.	1.9 °C/W
$R_{thj-amb}$	Thermal Resistance Junction-ambient	Max.	110 °C/W



Electrical Characteristics @ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	25	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to 25°C , $I_{\text{D}}=1\text{mA}$	-	0.037	-	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=33\text{A}$	-	-	9	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=20\text{A}$	-	-	18	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1	-	3	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=33\text{A}$	-	28	-	S
I_{DSS}	Drain-Source Leakage Current ($T_j=25^\circ\text{C}$)	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
	Drain-Source Leakage Current ($T_j=150^\circ\text{C}$)	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}$	-	-	25	μA
I_{GSS}	Gate-Source Leakage	$V_{\text{GS}}= \pm 20\text{V}$	-	-	± 100	nA
Q_g	Total Gate Charge ²	$I_{\text{D}}=33\text{A}$	-	23	-	nC
Q_{gs}	Gate-Source Charge		-	3	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge		-	17	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time ²	$V_{\text{DS}}=15\text{V}$ $I_{\text{D}}=33\text{A}$	-	8.8	-	ns
t_r	Rise Time		-	95	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	24	-	ns
t_f	Fall Time		-	14	-	ns
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$ $V_{\text{DS}}=25\text{V}$	-	790	-	pF
C_{oss}	Output Capacitance		-	475	-	pF
C_{rss}	Reverse Transfer Capacitance		f=1.0MHz	-	195	-

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
I_s	Continuous Source Current (Body Diode)	$V_D=V_G=0\text{V}, V_S=1.26\text{V}$	-	-	66	A
I_{SM}	Pulsed Source Current (Body Diode) ¹		-	-	210	A
V_{SD}	Forward On Voltage ²	$T_j=25^\circ\text{C}, I_s=66\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.26	V

Drain-Source Avalanche Ratings

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
E_{AS}	Single Pulse Avalanche Energy ²	$V_{\text{DD}}=25\text{V}, I_{\text{D}}=35\text{A}, L=100\mu\text{H}$	-	-	61	mJ
I_{AR}	Avalanche Current		$V_{\text{GS}}=10\text{V}$	-	-	A

Notes:

- 1.Pulse width limited by safe operating area.
- 2.Pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.

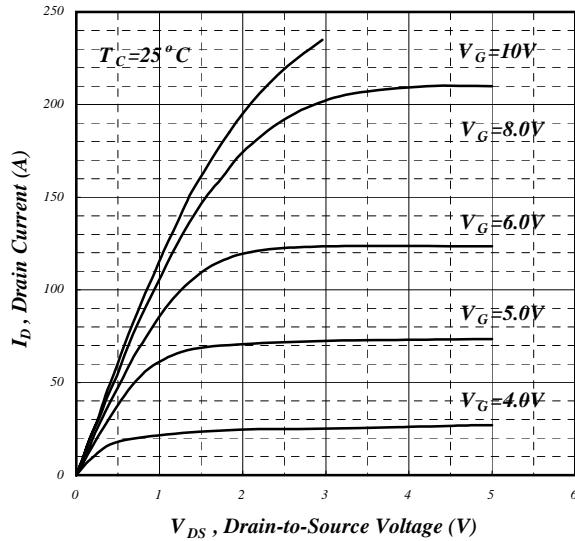


Fig 1. Typical Output Characteristics

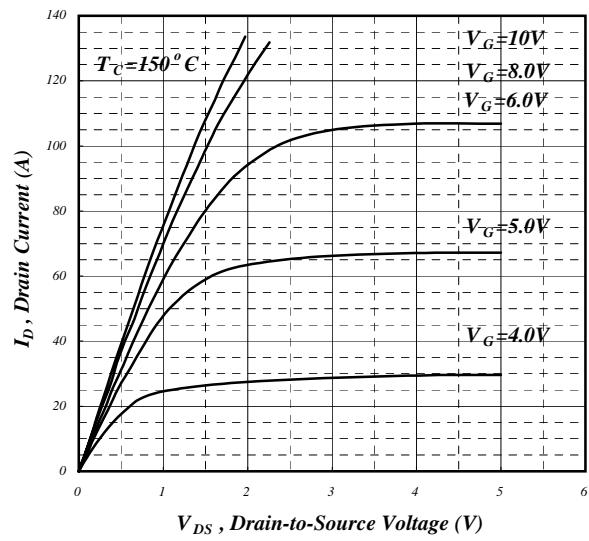


Fig 2. Typical Output Characteristics

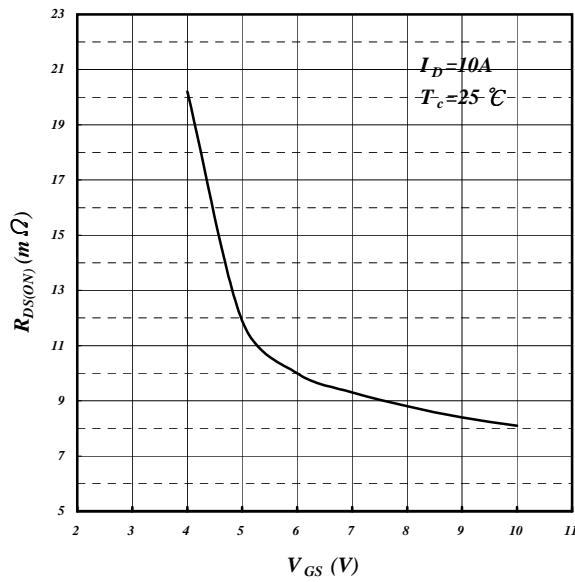


Fig 3. On-Resistance v.s. Gate Voltage

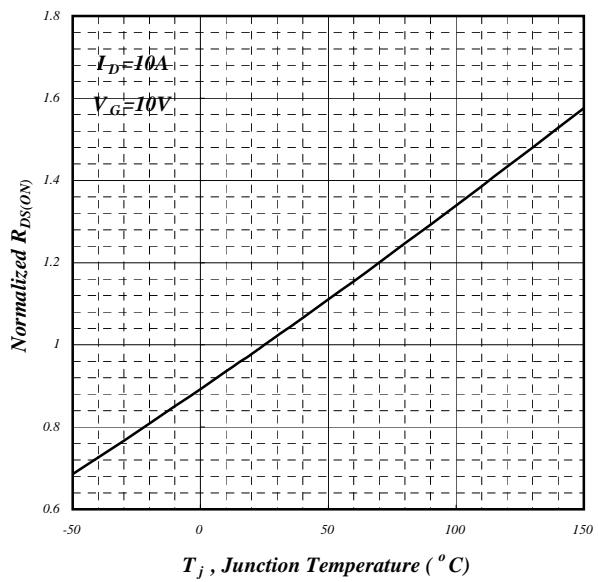
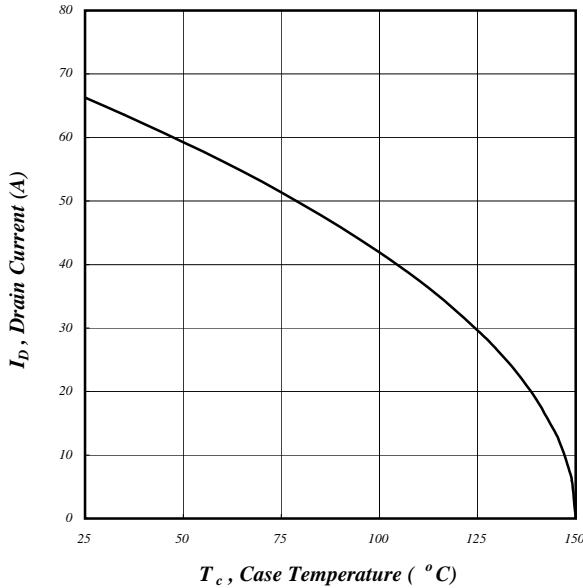


Fig 4. Normalized On-Resistance v.s. Junction Temperature



**Fig 5. Maximum Drain Current v.s.
Case Temperature**

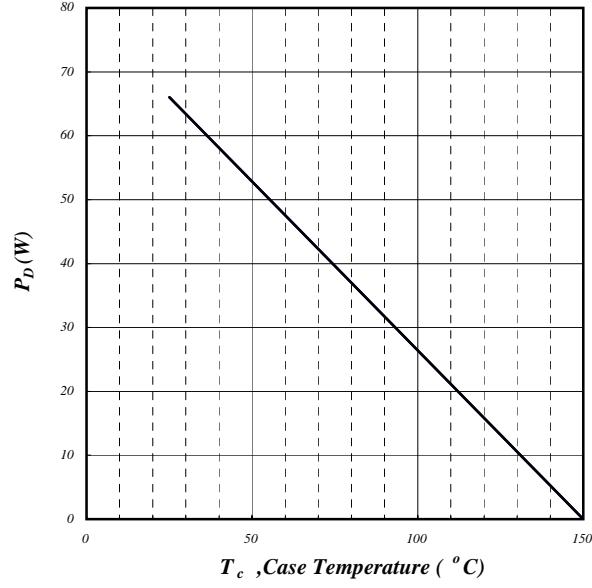


Fig 6. Typical Power Dissipation

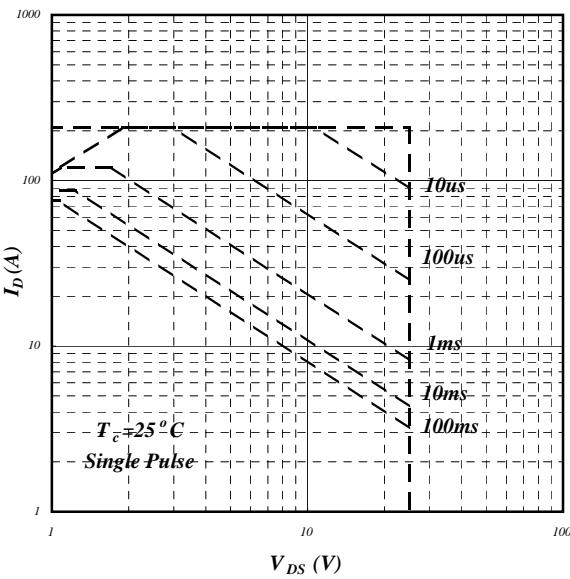


Fig 7. Maximum Safe Operating Area

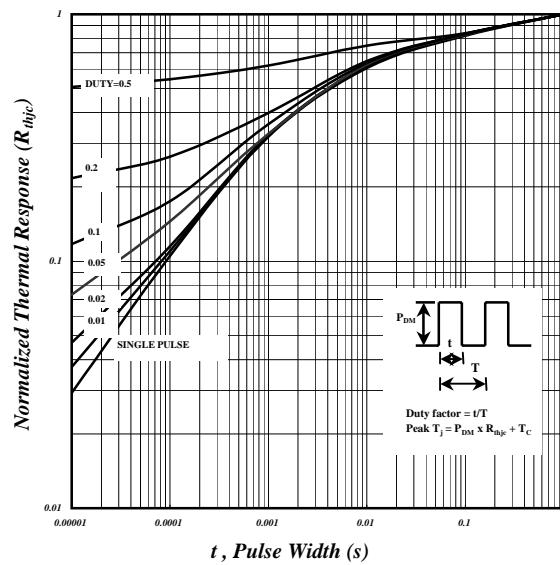


Fig 8. Effective Transient Thermal Impedance



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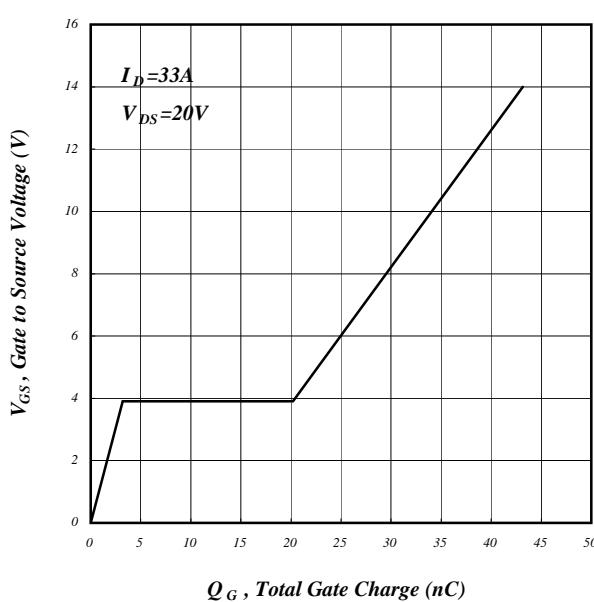


Fig 9. Gate Charge Characteristics

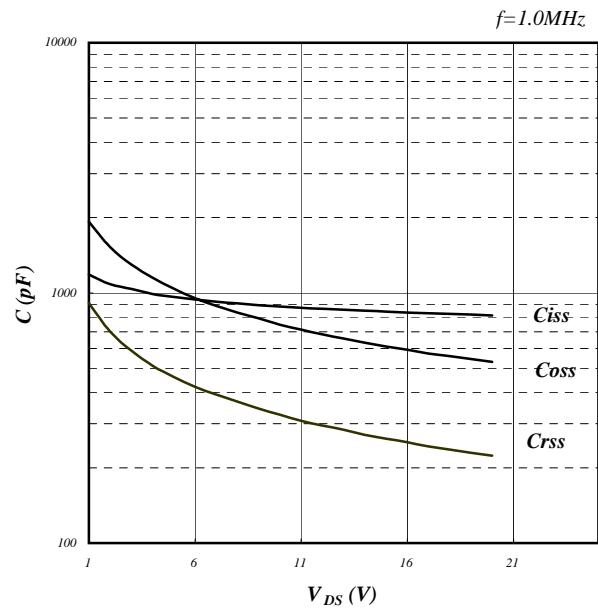


Fig 10. Typical Capacitance Characteristics

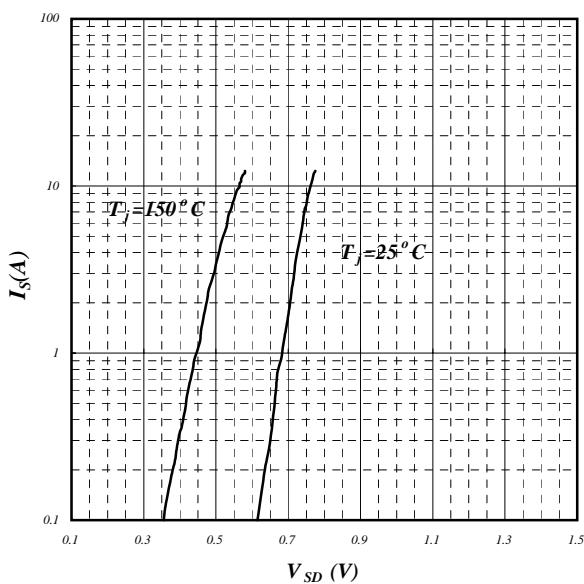


Fig 11. Forward Characteristic of Reverse Diode

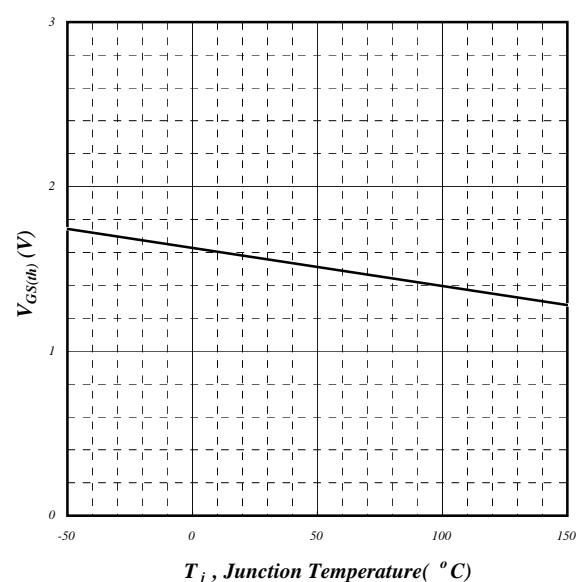


Fig 12. Gate Threshold Voltage v.s. Junction Temperature



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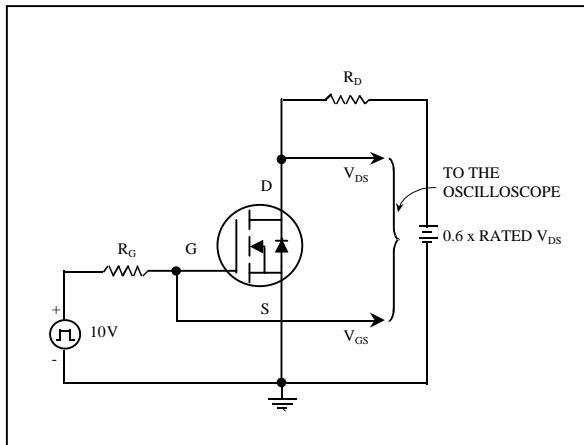


Fig 13. Switching Time Circuit

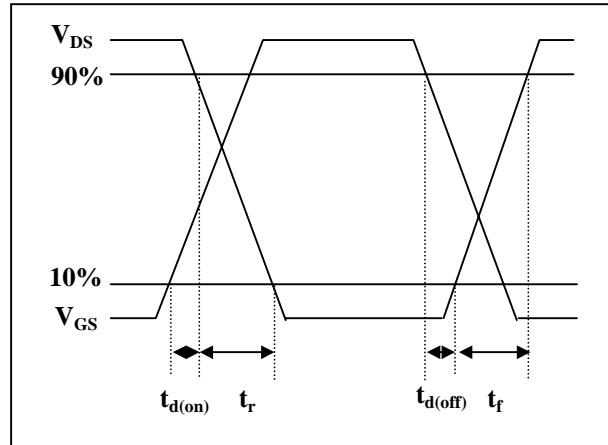


Fig 14. Switching Time Waveform

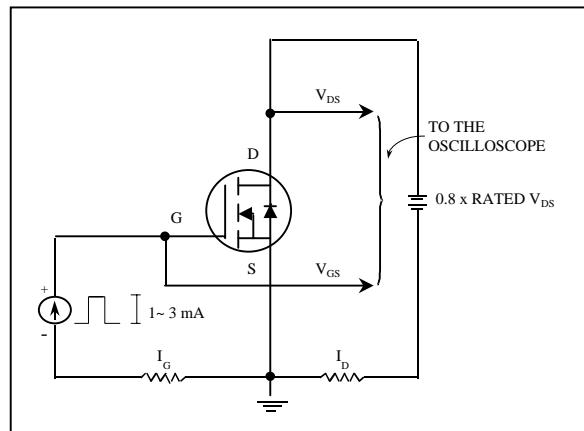


Fig 15. Gate Charge Circuit

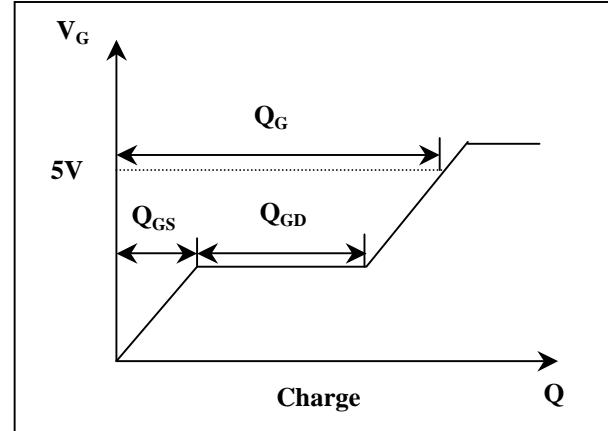


Fig 16. Gate Charge Waveform